PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4187110

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the DU, YAND previously recorded on Reel 029797 Frame 0134. Assignor(s) hereby confirms the DU, YANG.

CONVEYING PARTY DATA

Name	Execution Date
YANG DU	02/04/2013

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13765061

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (919) 238-2300

Email: avangorder@wt-ip.com
Correspondent Name: W&T/QUALCOMM

Address Line 1: 106 PINEDALE SPRINGS WAY
Address Line 4: CARY, NORTH CAROLINA 27511

ATTORNEY DOCKET NUMBER:	122814/1173-073
NAME OF SUBMITTER:	ALLYSON W. VAN GORDER
SIGNATURE:	/Allyson W. Van Gorder/
DATE SIGNED:	12/15/2016

Total Attachments: 9

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PATENT REEL: 040980 FRAME: 0854

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PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yand Du	02/04/2013

RECEIVING PARTY DATA

Name:	QUALCOMM Incorporated	
Street Address:	5775 Morehouse Drive	
Internal Address:	Patent Department	
City:	San Diego	
State/Country:	CALIFORNIA	
Postal Code:	92121-1714	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13765061

CORRESPONDENCE DATA

Fax Number: 8586582502 **Phone:** 858-658-5787

Email: Patent.Docketing.US@qualcomm.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: QUALCOMM Incorporated Address Line 1: 5775 Morehouse Drive Address Line 2: Patent Department

Address Line 4: San Diego, CALIFORNIA 92121-1714

ATTORNEY DOCKET

NUMBER:

122814

NAME OF SUBMITTER:

Nicholas J. Pauley

Signature:

/Nicholas J. Pauley/

Date:

02/12/2013

Total Attachments: 2

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 EPAS ID:
 PAT2268501

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 02/12/2013

 Fee Amount:
 \$40

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ASSIGNMENT

WHEREAS, I,

1. Yang Du, a citizen of the United States, having a mailing address of 5775 Morehouse Drive, San Diego, CA 92121; and a resident of Carlsbad, California

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to THREE-DIMENSIONAL (3-D) INTEGRATED CIRCUITS (3DICS) WITH GRAPHENE SHIELD, AND RELATED COMPONENTS AND METHODS (collectively the "INVENTIONS") for which I have executed and/or may execute one or more patent applications therefor, and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I do hereby acknowledge that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but limited U.S. Application 13765061 not to No(s). February 12, 2013 Qualcomm Reference No. 122814 provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND I further do acknowledge and agree that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of

PATENT REEL: 040980 FRAME: 0858 addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND I DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND I DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which I may be entitled, or that I may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND I HEREBY covenant and agree that I will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND I HEREBY represent that I have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that I have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at $\frac{S_{24}D_{1}e_{20}}{LOCATION}$, on $\frac{O2/O4/2O/3}{DATE}$ $\frac{\sqrt{Y_{AB}}}{Y_{AB}}$

Yang Du

ASSIGNMENT

WHEREAS, I,

1. Yang Du, a citizen of the United States, having a mailing address of 5775 Morehouse Drive, San Diego, CA 92121; and a resident of Carlsbad, California

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to THREE-DIMENSIONAL (3-D) INTEGRATED CIRCUITS (3DICS) WITH GRAPHENE SHIELD, AND RELATED COMPONENTS AND METHODS (collectively the "INVENTIONS") for which I have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I do hereby acknowledge that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but 13/765,061 not limited to U.S. Application No(s). February 12, 2013 ___, Qualcomm Reference No. <u>122814</u> provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND I further do acknowledge and agree that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of

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addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND I DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument:

AND I DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which I may be entitled, or that I may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND I HEREBY covenant and agree that I will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries:

AND I HEREBY represent that I have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that I have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Son Diego, on OZ/04/2013
LOCATION DATE



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CONVEYING PARTY DATA

Name	Execution Date
YANG DU	02/04/2013

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13765061

CORRESPONDENCE DATA

PATENT REEL: 040980 FRAME: 0862/2016 1:46 PM Fax Number:

Phone: (919) 238-2300
Email: avangorder@wt-ip.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if

provided; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: W&T/QUALCOMM

Address Line 1: 106 PINEDALE SPRINGS WAY
Address Line 4: CARY, NORTH CAROLINA 27511

and and and and	ATTORNEY DOCKET NUMBER:	122814/1173-073
-	NAME OF SUBMITTER:	ALLYSON W. VAN GORDER
-	Signature:	/Allyson W. Van Gorder/
	Date:	11/21/2016

Total Attachments: 6

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RECORDED: 12/15/2016

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